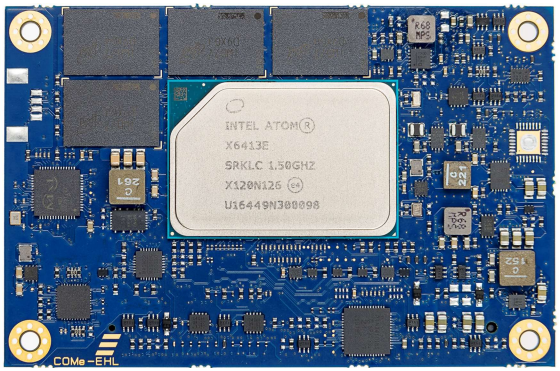
ENGICAM EMBEDDED SOLUTIONS

MATLOG NEATECH Group

COM Express®

COMe 10M- EHl

The new Engicam COMe module, based on Intel® processors ELKHART LAKE ™ series ATOM® x6000E, Pentium® and Celeron®. CPU and graphics performance with integrated IoT features, real-time performance, manageability, security, and functional safety.



HIGHLIGHTS

- Standard COM Express ® Mini type 10
- Suitable for IoT and real time performance
- Ethernet interface up to 2.5 Gb
- DP/HDMI up to 4096x2160@60Hz

APPLICATIONS

Industrial | Digital Signage Infotainment | Transportation | Automotive | Avionics | Surveillance | Robotics | Biomedical/ Medical devices | Home Automation

FEATURES

Windows 10

CPU	• Intel Atom X6211E Dual Core @ 1.2 GHz (burst 3.0 GHz) 1.5MB L2 cache, 6W • Intel Atom X6413E Quad Core @ 1.5 GHz (burst 3.0 GHz) 1.5MB L2 cache, 9W • Intel Atom X6425E Quad Core @ 1.8 GHz (burst 3.0 GHz) 1.5MB L2 cache, 12W) • Intel Atom X6212RE Dual Core @ 1.2 GHz, 1.5MB L2 cache, 6W • Intel Atom X6414RE Quad Core @ 1.5 GHz, 1.5MB L2 cache, 9W • Intel Atom X6425RE Quad Core @ 1.9 GHz, 1.5MB L2 cache, 12W
CORES	Up to 4
MEMORY	Up to 16GB LPDDR4
GRAPHICS	• Intel 11th generation (Gen 11) LP graphics controller. • DirectX 12.1 compliant, OpenGL ES 3.1/3.0/2.0/1.1, OpenGL 4.5 supported, OpenCL™ 1.2, Vulkan 1.0 APIs, Dedicated FIVR for Graphics, Intel Virtualization Technology for Directed I/O (VT-d)
VIDEO INTERFACES	• HDMI/DP • eDP/LVDS
VIDEO PROCESSING	• HEVC/H.265, H.264, VP9, VP8, WMV9/VC1, MPEG-2, VC-1. JPEG/MJPEG dec • HEVC/H.265, H.264, VP9, JPEG/MJPEG enc
AUDIO	HDA Interface

NETWORKING	Ethernet interface up to 2.5 Gb
MASS STORAGE	• 2x SATA • Starting from 4GB eMMC drive soldered on-board
USB	• 2 x USB HOST 3.1 • 8 x USB HOST 2.0
PCIE	6 x PCIe 3.0
PERIPHERAL INTERFACES	SDIO, SM Bus, I²C, LPC/eSPI, SPI, UART/CAN(optional), GPIOs
POWER SUPPLY	+5 to 20 V DC
OPERATING SYSTEM	• Ubuntu • Windows 10
OPERATING TEMPERATURE*	Industrial (-40°C to 110°C Tj)
DIMENSIONS	55 x 84 mm

* Valid for all components except CPU. Customer shall consider junction temperature for CPU. Temperature will widely depend on application. Specific cooling solutions could be necessary for the final system.

intel partner Gold

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BLOCK DIAGRAM